

ICS 77.150.99

CCS H 68



**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 26307-2025

Replacing GB/T 26307-2010

Silver target

银靶材

Issued on: August 29, 2025

Implemented on: March 1, 2026

**Issued by: State Administration for Market Regulation;
Standardization Administration of the PRC**

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Foreword

This document complies with the provisions of GB/T 1.1-2020 "Standardization Work Guidelines Part 1: Structure and Drafting Rules of Standardization Documents". Drafting.

This document replaces GB/T 26307-2010 "Silver Target". Compared with GB/T 26307-2010, the main differences are structural adjustments and editorial changes.

In addition, the main technological changes are as follows.

- a) Added terms and definitions (see Chapter 3);
 - (b) Added requirements for the classification and chemical composition of products with Ag99.995 purity, as well as the corresponding test methods (see 4.1.1, 5.1,...). 6.1);
 - c) Added requirements for product structure (see 4.1.2);
 - d) Added product marking requirements (see 4.2);
 - e) The grain size requirement has been changed from "the average lateral grain size of the silver target should be between 50 μm and 150 μm " to "the average lateral grain size of the product..." The particle size should not exceed 150 μm (see 5.2, 3.3 of the 2010 edition);
 - f) Added provisions regarding internal product quality requirements, testing methods, and the determination of test results (see 5.3, 6.3, and 7.4.2);
 - g) Added provisions regarding product welding quality requirements, test methods, and judgment of inspection results (see 5.5, 6.5, and 7.4.2);
 - h) The product dimensions and their tolerance requirements have been changed from overall product dimensions to product dimensions excluding the back panel (see [link]).
- 5.6 (3.6 in the 2010 version);

i) The product grain size analysis method has been changed, and Appendix A, "Detection Method for On-site Metallographic Determination of the Transverse Average Grain Size of a Silver Target," has been deleted.

(See 5.2, Appendix A of the 2010 edition);

j) Product inspection items and sampling requirements have been added (see 7.3);

k) Added relevant content to the product accompanying documents and order forms (see 8.3, Chapter 9).

Please note that some content in this document may involve patents. The issuing organization of this document assumes no responsibility for identifying patents.

This document was proposed by the China Nonferrous Metals Industry Association.

This document is under the jurisdiction of the National Technical Committee on Standardization of Nonferrous Metals (SAC/TC243).

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This document was first published in 2010, and this is its first revision. Silver sputtering target

1 Scope

This document specifies the classification and marking, technical requirements, test methods, inspection rules and marking, packaging, transportation, storage and accompanying materials for silver sputtering targets.

Documents and purchase orders.

This document applies to all types of silver sputtering targets used in semiconductor devices. Silver targets for other applications should refer to this document for further information.

2 Normative references

GB/T 1031

GB/T 4135

GB/T 6394

GB/T 8651

GB/T 11067

GB/T 15077

GB/T 36590

GB/T 39810

3 Terms and Definitions

The following terms and definitions apply to this document.

3.1 target

The cathode portion in sputter deposition technology.

Note. The cathode material is deposited on the anode surface in the form of molecules, atoms or ions, detached from the cathode under the impact of positively charged cations.

3.2 targetblank

The portion of the cathode used as the target material.

3.3 backing plate

The part used to support or fix the target blank.

Note. The target material and the backing plate are connected by brazing.